Docket No.: LPTF64

Form 1595 (Rev. 09/04)

RECORDATION FORM COVER SHEET

U. S. Department of Commerce
Patent and Trademark Office

PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below

1. Name of conveying party(ies) with the execution date:

WENJIE HU, November 26, 2009
ZENGHUI SUN, November 26, 2009
HONGYU LIU, November 26, 2009
GANG WANG, November 26, 2009
XIBIN SHAO, November 26, 2009

2. Name/address of receiving Party(ies)

BOE TECHNOLOGY GROUP CO., LTD.

NO. 10, JIUXIANQUAO ROAD, CHAOYANG,
BEIJING 100016, CHINA

Add'1 names of receiving parties Attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Security Agreement
☐ Merger ☐ Change of Name
☐ Reassignment ☐ Other

4. Application number(s) or patent number(s):

A. Patent Application No. (s)

12/628,878

B. Patent No.(s)

Additional number attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

J. C. Patents
4 Venture, Suite 250
Irvine, CA 92618
(949) 660-0761

Atty Docket No.: LPTF64

6. Total No. of applications and patents involved:

ONE (1)

7. Total fee(37CFR§3.41): $ 40.00

☐ Authorized to be charged by credit card
☒ Authorized to be charge to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. **Payment Information**

a. Credit Card Last 4 Numbers ________.
Expiration Date ________.
b. Deposit Account Number 50-0710
Authorized User Name Jiawei Huang

9. Statement and Signature:

To the best of my knowledge and belief, the forging information is true and Correct and any attached copy is a true copy of the original document.

Jiawei Huang
Name of person Signing
Registration No. 43,330

Signature

12-1-2009
Date

Total number of pages including cover sheet, attachments, and documents: 3

CH $40.00 500710 12628878

ASSIGNMENT

WHEREAS, the undersigned Inventors:

HU, Wenjie;
SUN, Zenghui;
LIU, Hongyu;
WANG, Gang;
SHAO, Xibin

have invented certain new and useful improvements as described and set forth in the below identified application for United States Patent:

Title: **METHOD FOR MANUFACTURING E-PAPER ARRAY SUBSTRATE AND E-PAPER ARRAY SUBSTRATE**

[ ] Filed on: ______ Serial No.: ______
[X] Executed concurrently with the execution of this instrument

WHEREAS **BOE TECHNOLOGY GROUP CO., LTD.**
(hereinafter termed "Assignee"), a China corporation
residing at No.10 jiuxianqiao RD, Chaoyang,
Beijing 100016, P.R. China

desires to acquire the entire right, title, and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or disclosed jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and al patents, certificates of invention and other forms of protection thereon (hereinafter termed "patents") applied for or granted in the United States and/or other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by each of said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey to said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply in any or all countries of the world for patents, certificates of inventions or other governmental grants on said invention, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial Property or pursuant to any other convention, treaty, agreement or understanding; (c) in and to any and all applications filed and any and all patents, certificates of inventions or other governmental grants granted on said invention in the United States or any other country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; (d) in and to each and every reissue or extension of any of said patents; and (e) in and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.

2. Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and other countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance

all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of said applications; (d) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (e) for filing and prosecuting applications for reissue of any of said patents; (f) for interference or other priority proceedings involving said invention; and (g) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this Assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.

4. Said Inventors hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

Full name of the sole or first inventor: **HU, Wenjie**

Inventor's signature: 胡文杰 Date: 09. 11. 26

Full name of the second inventor: **SUN, Zenghui**

Inventor's signature: 孙增辉 Date: 09. 11. 26

Full name of the third inventor: **LIU, Hongyu**

Inventor's signature: 刘宏宇 Date: 09. 11. 26

Full name of the fourth inventor: **WANG, Gang**

Inventor's signature: 王刚 Date: 09. 11. 26

Full name of the fifth inventor: **SHAO, Xibin**

Inventor's signature: 邵喜斌 Date: 09. 11. 26